

500V N-Channel MOSFET

FEATURES

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

| TO-220F GDS | |
|-------------|--|
| | |

| Device Marking and Package Information | | | | |
|----------------------------------------|---------|-----------|--|--|
| Device | Package | Marking | | |
| CS13N50FF | TO-220F | CS13N50FF | | |

| Absolute Maximum Ratings $T_c = 25^{\circ}C$, unless otherwise noted | | | | |
|------------------------------------------------------------------------------|-----------------------------------|----------|------|--|
| Parameter | Symbol | Value | Unit | |
| Drain-Source Voltage (V _{GS} = 0V) | V _{DSS} | 500 | V | |
| Continuous Drain Current | I _D | 13 | А | |
| Pulsed Drain Current (note1) | I _{DM} | 52 | А | |
| Gate-Source Voltage | V _{GSS} | ±30 | V | |
| Single Pulse Avalanche Energy (note2) | E _{AS} | 352.8 | mJ | |
| Avalanche Current (note1) | I _{AS} | 8.4 | А | |
| Repetitive Avalanche Energy (note1) | E _{AR} | 1.4 | mJ | |
| Power Dissipation (T _C = 25°C) | P _D | 49 | W | |
| Operating Junction and Storage Temperature Range | T _J , T _{stg} | -55~+150 | ٥C | |

| Thermal Resistance | | | | |
|-----------------------------------------|-------------------|-------|------|--|
| Parameter | Symbol | Value | Unit | |
| Thermal Resistance, Junction-to-Case | R _{thJC} | 2.55 | °C/W | |
| Thermal Resistance, Junction-to-Ambient | R _{thJA} | 62.5 | | |

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CS13N50FF

| Specifications $T_J = 25^{\circ}C$, unless otherwise noted | | | | | | |
|--------------------------------------------------------------------|------------------------|---------------------------------------------------------------------|-------|-------|------|------|
| Parameter | Symbol Test Conditions | | Value | | | Unit |
| rarameter | Symbol | rest conditions | Min. | Тур. | Max. | Unit |
| Static | | | ī | ĩ | - | |
| Drain-Source Breakdown Voltage | V _{(BR)DSS} | $V_{GS} = 0V, I_D = 250\mu A$ | 500 | | | V |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{DS} = 500V, V_{GS} = 0V, T_{J} = 25^{\circ}C$ | | | 1 | μA |
| Gate-Source Leakage | I _{GSS} | V_{GS} = $\pm 30V$ | | | ±100 | nA |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | 3.0 | | 4.0 | V |
| Drain-Source On-Resistance (Note3) | R _{DS(on)} | V _{GS} = 10V, I _D = 6.5A | | 0.39 | 0.46 | Ω |
| Dynamic | 1 | | | | | |
| Input Capacitance | C _{iss} | | | 1569 | | |
| Output Capacitance | C _{oss} | VGS = 0V, | | 171 | | pF |
| Reverse Transfer Capacitance | C _{rss} | VDS = 25V, f = 1.0MHz | | 5 | | |
| Internal Gate Resistance | Rg | | | 3.1 | | Ω |
| Total Gate Charge | Q _g | | | 30.9 | | |
| Gate-Source Charge | Q _{gs} | $V_{DD} = 400V, I_D = 13A, V_{GS} = 10V$ | | 7.8 | | nC |
| Gate-Drain Charge | Q _{gd} | | | 10.6 | | |
| Turn-on Delay Time | t _{d(on)} | | | 43.2 | | |
| Turn-on Rise Time | t _r | V _{DD} = 250V, I _D =13A, | | 24.8 | | |
| Turn-off Delay Time | t _{d(off)} | V_{DD} = 250V, I _D =13A, R _G = 25 Ω | | 131.8 | | ns |
| Turn-off Fall Time | t _f | | | 42.6 | | |
| Drain-Source Body Diode Character | stics | | | | | |
| Continuous Body Diode Current | ۱ _s | T _C = 25 °C | | | 13 | А |
| Pulsed Diode Forward Current | I _{SM} | | | | 52 | |
| Body Diode Voltage | V _{SD} | T _J = 25°C, I _{SD} = 6.5A, V _{GS} = 0V | | | 1.4 | V |
| Reverse Recovery Time | t _{rr} | V _R = 250V,I _S = 13A, | | 307 | | ns |
| Reverse Recovery Charge | Q _{rr} | di _F /dt =100A /µs | | 3.5 | | μC |

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. L = 10.0mH, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 °C

3. Pulse Test: Pulse width \leq 300µs, Duty Cycle \leq 1%



Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted

Figure 1. Output Characteristics (T_J = 25°C)

Figure 2. Body Diode Forward Voltage

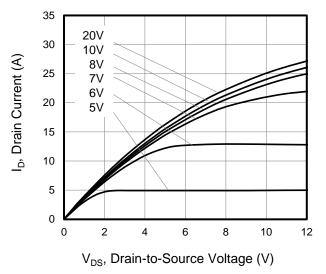
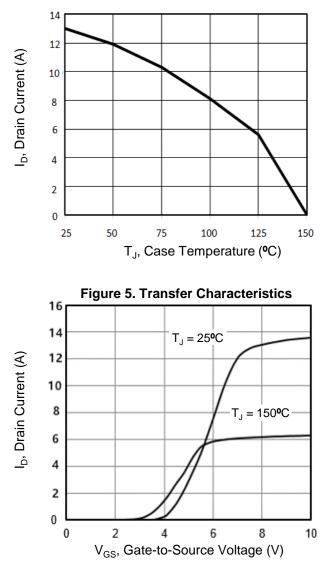


Figure 3. Drain Current vs. Temperature



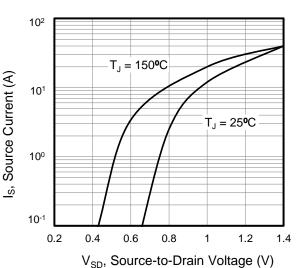


Figure 4. BV_{DSS} Variation vs. Temperature

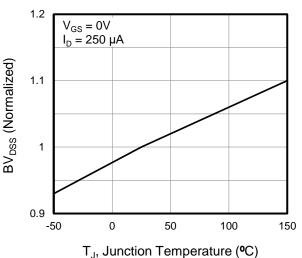
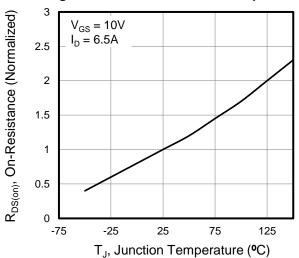


Figure 6. On-Resistance vs. Temperature





Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted

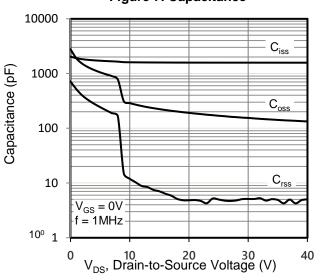


Figure 7. Capacitance

Figure 8. Gate Charge

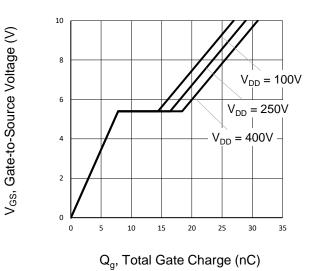
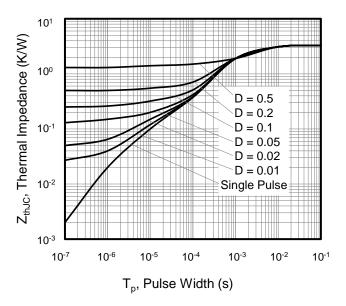


Figure 9. Transient Thermal Impedance







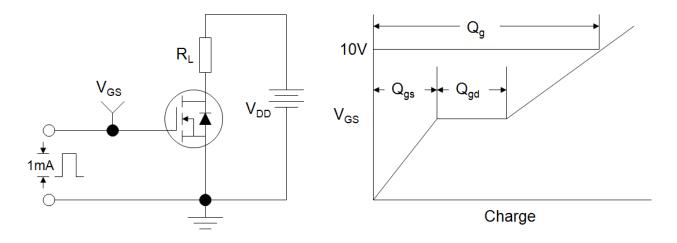


Figure B: Resistive Switching Test Circuit and Waveform

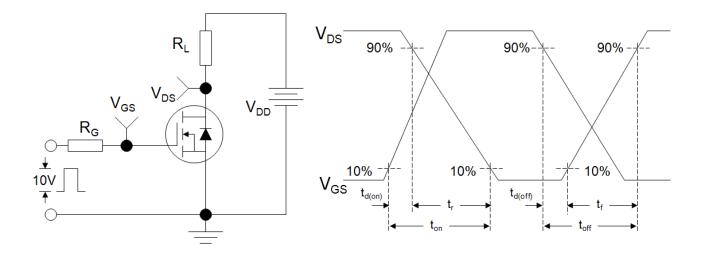
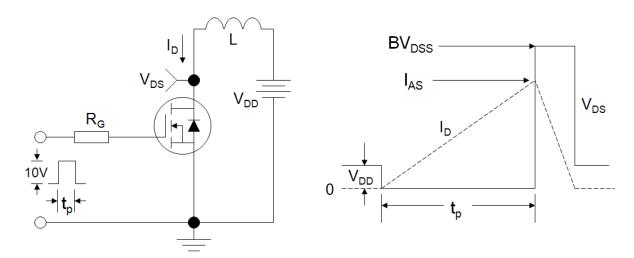
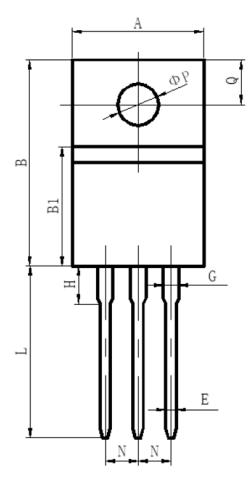


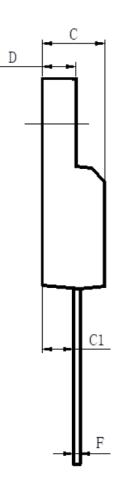
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-220F





| SYMBOLS | MILLIMETERS | | | |
|-----------|-------------|-------|--|--|
| STIVIBULS | MIN | MAX | | |
| Α | 9.70 | 10.30 | | |
| В | 15.50 | 16.10 | | |
| B1 | 8.99 | 9.39 | | |
| C | 4.40 | 4.80 | | |
| C1 | 2.15 | 2.55 | | |
| D | 2.50 | 2.90 | | |
| E | 0.70 | 0.90 | | |
| F | 0.40 | 0.60 | | |
| G | 1.12 | 1.42 | | |
| Н | 3.40 | 3.80 | | |
| L | 12.60 | 13.60 | | |
| N | 2.34 | 2.74 | | |
| Q | 3.15 | 3.55 | | |
| ΦΡ | 3.00 | 3.30 | | |



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